X-1574 US 10/796,471

**PATENT** Conf. No.: 2282

## IN THE UNITED STATES PATENT OFFICE

Ápplicant:

Leilei Zhang

Assignee:

Xilinx, Inc.

Title:

Metal Lid with Improved Adhesion to Package Substrate

Serial No.:

10/796,471

Filing Date: March 9, 2004

Examiner:

Jose R. Diaz

Art Unit:

2815

Docket No.: X-1574 US

Conf. No.:

2282

Mail Stop AF Commissioner for Patents P.O. Box 1450

Alexandria, VA 22313-1450

## STATEMENT OF THE SUBSTANCE OF THE INTERVIEW

Sir:

The undersigned sincerely thanks Examiner Jose R. Diaz for the telephonic interview on November 30, 2006, and submits this Statement of the Substance of the Interview ("Statement") in accordance with 37 C.F.R. § 1.133. This Statement is being filed with a Response to the Final Office Action. . .

The participants in the telephonic interview were Examiner Jose R. Diaz, and Mr. Scott W. Hewett, attorney for the Applicant.

No exhibit was shown and no demonstration was conducted.

Claim 11 was discussed in light of the objections to the drawings for failure to describe a gap. The enablement of claim 1 was discussed, including reference to U.S. Patent No. 6,654,448 by Fishley et al. Arguments in support of the enablement of claims 1-21, 31, and 31 are included in the Response to the Final Office Action filed herewith. No amendments to the claims were proposed, and no amendments to the claims are made in the Response to the Final Office Action.

The Examiner suggested adding a section line to Fig. 2B to more clearly indicate the cross section represented by Fig. 2A. Fig. 2B and its associated portion of the written description are amended accordingly in the Response to the Final Office

X-1574 US PATENT 10/796,471 Conf. No.: 2282

Action. The Examiner also suggested indicating that the space around the chip capacitors in Fig. 2A is not filled with encapsulant. A reference numeral and lead line is added to Fig. 2A and the written description is amended in the Response to the Final Office Action to indicate this space. Mr. Hewett suggested copying the language of claim 11 into the written description so that the term "gap" was described. The written description is amended to this effect in the Response to the Final Office Action:

No amendments to the claims were proposed, and no agreement regarding the claims was reached. It was agreed that the matters discussed in the interview would be addressed in the Response to the Final Office Action for the Examiner's consideration.

Respectfully Submitted

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TRANSMITTAL FORM (to be used for all correspondence after initial filing)		Application / Conf. No.	10/796,471 / 2282
		Filing Date	March 09, 2004
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		Examiner Name	Jose R. Diaz
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Express Mail Receipt No.		Patent No.	
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ENCLOSURES (check all that apply)			
X Fee Transmittal Form	┛ (with R ¬	ment Papers tecordation Cover Sheet)	After Allowance Communication to
X Amendment / Reply Preliminary Amendment	Declaration / Oath		Appeal Communication to Board of Appeals and Interferences
After Final  Affidavit(s)/declaration(s)	_	ng(s) Replacement Sheets ing-related Papers	Appeal Communication to Group (Appeal Notice, Brief, Reply Brief)
Extension of Time Request	☐ ☐ Petition	-	Status Letter
Change Status to LARGE ENTITY			X Return Receipt Postcard
Express Abandonment Request To Con			<u> </u>
Provisi		onal Application of Attorney, Revocation	Other Enclosure(s) (please identify below):  One reference:
X Information Disclosure Statement Power Chang Address		e of Correspondence	Statement of the Substance of the Interview
X Substitute PTO-1449(s) Termin		al Disclaimer	
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Remarks Response to Missing Parts/			
Incomplete Application  Response to Missing			
Parts under 37 CFR 1.52 or 1.53			
SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT			
		<b>24309</b> (Clustomer Number)	Reg. Number 52,992
Signature R ( )			
Date  December 13, 2006  Charge an additional fees required/credit any overpayment to our Deposit Account Number: 24-0040			
CERTIFICATE OF MAILING			
Typed or Printed Name Pat Tompkins			
Signature December 13, 2006			

This collection of information is rrequired by 37 CFR 1.17 and 1.27. The information is required to botain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 12 minutes to complete. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, Virginia 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450.